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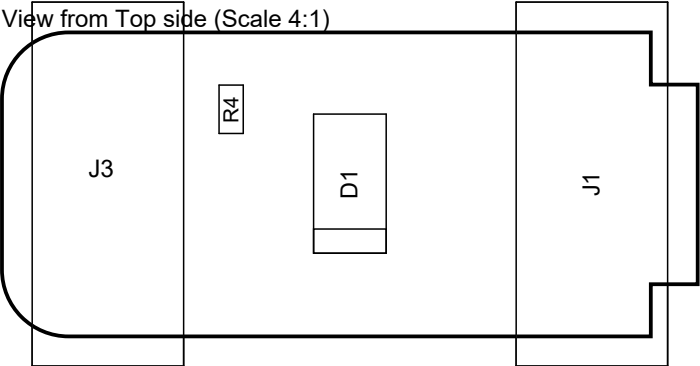
E

ASSEMBLY NOTES:

Assembly shall conform to IPC-A-610 Class 2.  
Assembly shall conform with RoHS Directive 2011/65/EU.  
Components shall be placed according to the associated CPL and BOM documents.  
Lead-free SAC305 solder shall be used.  
Reflow profile shall comply with J-STD-20C Lead-Free Reflow Profile.  
BGA components shall be 100% checked with x-ray for solder bridges after reflow.  
Finished assemblies shall be removed from panel prior to delivery.

Notes:

- 1Note 1
- 2Note 2
- 3Note 3



Title: <b>DM6010</b>	
Number: D0001093	Revision: R2M2 E2
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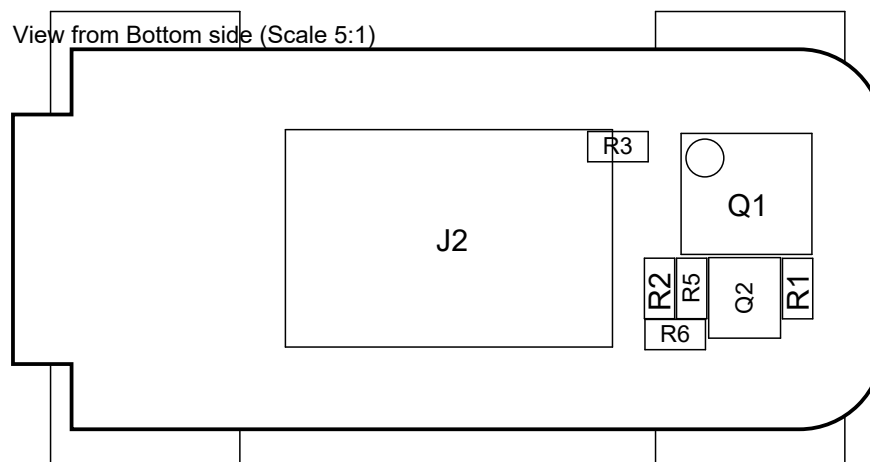
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Title: <b>DM6010</b>		
Number: D0001093	Revision: R2M2 E2	
Date: 11/10/2021	Sheet: 2 of 2	PROPRIETARY AND CONFIDENTIAL
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